

ABSTRACT OF THE DISCLOSURE

MULTILAYER PRINTED CIRCUIT BOARD AND PROCESS

FOR PRODUCING AND USING THE SAME

A process for producing a multilayer printed circuit board, comprising the steps of:

impregnating a thermosetting resin in a base material to form a prepreg,

applying an undercoating agent comprising

(a) a terminal-bifunctional linear epoxy resin having an average epoxy equivalent of from 450 to 6,000 and

(b) at least one component selected from the group consisting of 2-undecylimidazole, 1-cyanoethyl-2-undecylimidazole and 2,4-diamino-6-{2'-undecyl-imidazole(1')}-ethyl-s-triazine,

or

(a) a terminal-bifunctional linear epoxy resin having an average epoxy equivalent of from 450 to 6,000,

(b) an aromatic polyamine and

(c) at least one component selected from the group consisting of 2-undecylimidazole, 1-cyanoethyl-2-undecylimidazole and 2,4-diamino-6-{2'-undecyl-imidazole(1')}-ethyl-s-triazine

to at least one circuit side of an interlayer circuit board on at least one side of which circuit has been formed,

laying the prepreg on at least one side of the undercoating agent-applied interlayer circuit board and subjecting them to laminating press.

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The aromatic polyamide (b) preferably has sulfide linkage, sulfone linkage, sulfoxide linkage or ether linkage.

Desired properties of the multilayer printed circuit board were achieved with no oxidation treatment because of the improved adhesion property of the undercoating agent to copper foil.

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